

DATASHEET

1206 Package Chip Infrared LED With Inner Lens EAIST3015A2



Features

- · High reliability
- Small double-end package
- Peak wavelength λp=850nm
- Package in 8mm tape on 7" diameter reel
- Low forward voltage
- Pb free
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH

Descriptions

- EAIST3015A2 is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with flat top view lens.
- The device is spectrally matched with silicon photodiode and phototransistor.

Applications

- PCB mounted infrared sensor
- Infrared remote control units with high power requirement
- Smoke detector
- Infrared applied system

Device Selection Guide

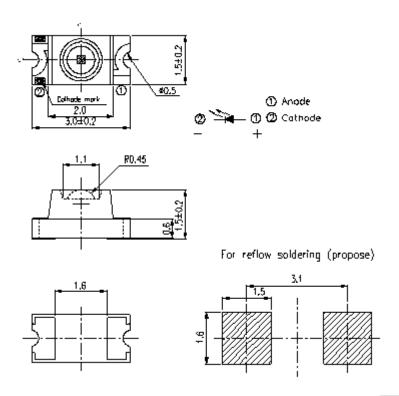
Part Category	Chip Material	Resin Color
EAIST3015A2	GaAlAs	Water Clear

LifecyclePhase:

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Package Dimensions



Notes: 1.All dimensions are in millimeters

- 2. Tolerances unless dimensions ±0.1mm
- 3. Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.



Absolute Maximum Ratings (Ta=25)

Parameter	Symbol	Rating	Units	
Continuous Forward Current	Current I _F 65		mA	
Reverse Voltage	V_{R}	5	V	
Operating Temperature	T_{opr}	-25 ~ +85		
Storage Temperature	T_{stg}	-40 ~ +85		
Soldering Temperature *1	T_{sol}	260		
Power Dissipation at(or below) 25 Free Air Temperature	P _d	130	mW	

Notes: *1. Soldering time 5 seconds.

Electro-Optical Characteristics (Ta=25)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Units	
Radiant Intensity	le	I _F =20mA	1.0	2.0	40.0	mW/sr	
		. I _F =100mA Pulse Width 100µs ,Duty 1%		10	_		
Peak Wavelength	λр	I _F =20mA		850	-	nm	
Spectral Bandwidth	Δλ	I _F =50mA	-	45		nm	
Forward Voltage		I _F =20mA		1.45	1.65		
	V_{F}	. I _F =100mA Pulse Width 100µs ,Duty 1%		1.80	2.40	V	
Reverse Current	I_R	V _R =5V			10	μΑ	
View Angle	201/2	I _F =20mA		75		deg	

Radiant Intensity Specifications for Bin Grading

Rank	Condition	Min.	Max.	Units
G	I _F =20mA	1.25	2.25	
Н		2.25	3.25	
J		3.25	4.25	
K		4.25	5.50	mW/sr
L		5.50	6.75	
М		6.75	8.00	
N1		8.00	40.00	



Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs. **Ambient Temperature**

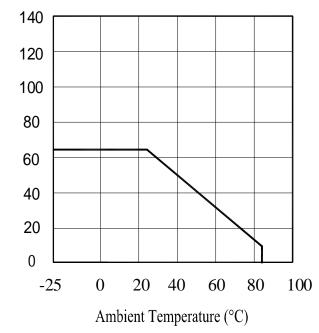


Fig.3 Forward Current vs.

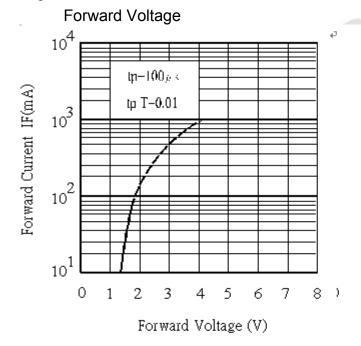


Fig.2 Spectral Distribution

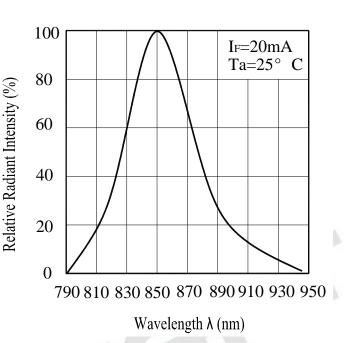
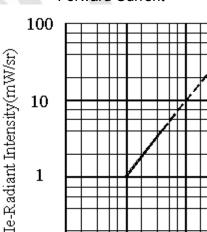
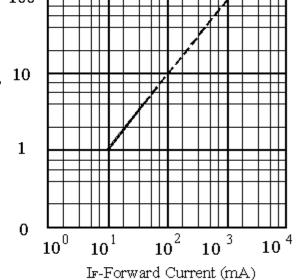


Fig.4 Relative Intensity vs. **Forward Current**





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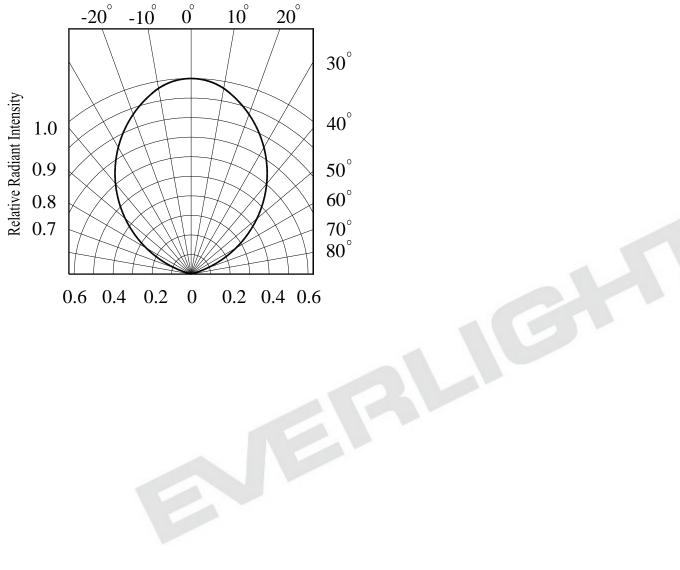
Forward Current (mA)



Typical Electro-Optical Characteristics Curves

Fig.5 Relative Radiant Intensity vs.

Angular Displacement



LifecyclePhase:

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Precautions For Use

1. Over-current-proof

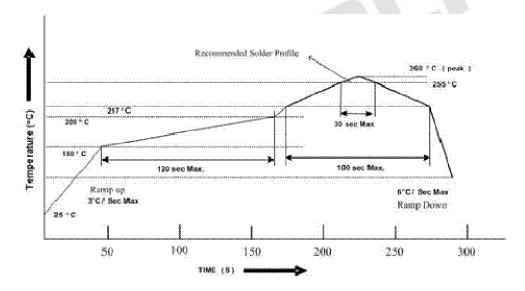
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 10 ~30 and 90%RH or less.
- 2.3 The LEDs suggested be used within one year.
- 2.4 After opening the package, the devices must be stored at 10°C~30°C and ≤ 60%RH, and used within 168 hours (floor life). If unused LEDs remain, it should be stored in moisture proof packages.
- 2.5 If the moisture absorbent material (desiccant material) has faded or unopened bag has exceeded the shelf life or devices (out of bag) have exceeded the floor life, baking treatment is required.
- 2.6 If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure or recommend the following conditions:
 - 96 hours at 60°C ± 5°C and < 5 % RH (reeled/tubed/loose units)

3. Soldering Condition

3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

6

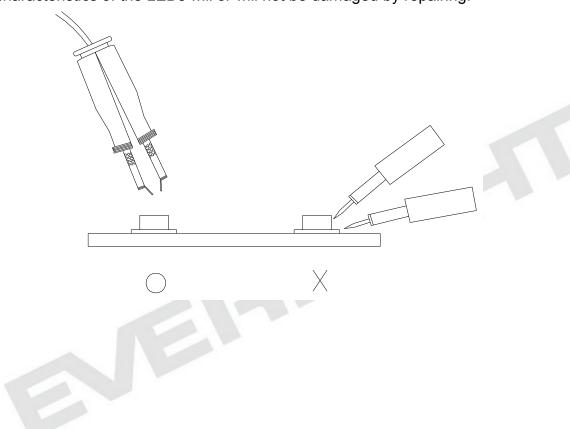


4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350 for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

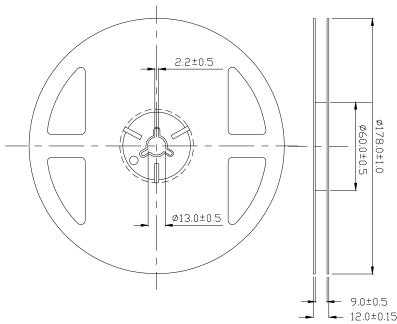
Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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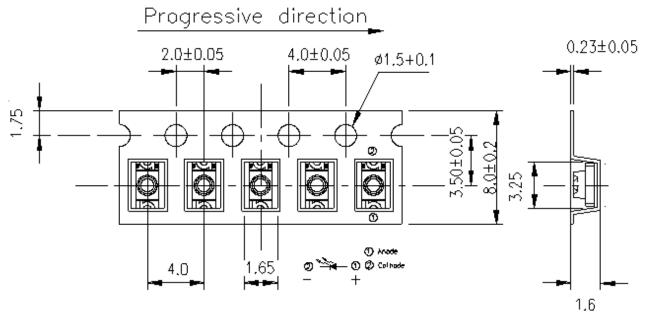


Package Dimensions



Note: The tolerances unless mentioned is ±0.1mm, Unit: mm

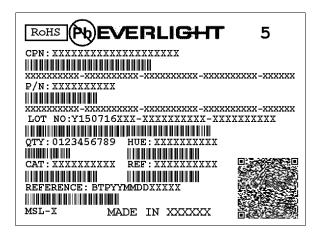
Carrier Taping Dimensions: Loaded Quantity Per Reel 2000PCS/Reel



Note: The tolerances unless mentioned is ±0.1mm, Unit: mm



Label Form Specification



CPN: Customer's Production Number

P/N : Production Number

LOT No: Lot Number QTY: Packing Quantity HUE: Peak Wavelength

CAT: Ranks

REF: Reference MSL-X: MSL Level

Made In: Manufacture place

Notes

- 1. Above specification may be changed without notice. Everlight Americas will reserve authority on material change for above specification.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. Everlight Americas assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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Expired Period: Forever